

Engis SC Diamond Polishing Compound for Mould Polishing

Engis Hyprez® SC diamond compound has been specially formulated for the fine polishing of large moulds.

In the past, a compound that cut quickly might leave a dull finish, resulting in additional finishing steps to bring the mould back to its original state, so time saved on the front end was lost in the final polish.

To address this challenge Engis has developed its SC diamond compound, which offers faster stock removal and fewer polishing steps, leading to lower costs, improved productivity and better quality components.

- New sharper diamond particles
- Optimized particle size distribution
- New carrier with superior lubricant qualities
- Better adhesion to the felt or wood bob
- Not 'greasy' like standard compounds
- Easier to view the workpiece while polishing
- Higher vaporization point

An exceptionally sharp diamond particle type has been selected and the Particle Size Distribution (PSD) optimized for superior cutting action.

In addition, Engis' new carrier formula has special lubricating properties so that larger moulds, which must often be polished in the moulding press, can be worked on before they have cooled.